

IN THE SPECIFICATION

Presented below are specification changes showing the changes made.

Please amend paragraph [0033] as follows:

[0033] **FIGS. 3A – 3B** also illustrate disk substrate 250 supported by Bernoulli gas flow and positioned above an embossing nest or die cavity 280. Pickup head 212 coupled to arm 204 supports disk substrate 250 below manifold body 213 and within an area defined by guide pins 262, 264. A third guide pin (not shown) may be disposed equidistant from guide pins 262, 264. Pickup head 212 may be positioned to hover disk substrate 250 above die assembly 230 that includes lower die portion 232. A disk receiving nest 280 for disk substrate 250 is formed near a top surface of lower die portion 232, as well as embossing foil 282 disposed above receiving nest 280 and below disk substrate 250. In one embodiment, pickup head 212 may precisely control the lowering of disk substrate 250 to about 0.5 mm above receiving nest 280 of lower die portion 232. At this point, the Bernoulli support by pickup head 212 may be stopped, and disk substrate 250 may float on a cushion of gas flowing on a surface of receiving nest ~~432~~ 280 that also constrains disks substrate to an area defined by the walls of receiving nest ~~432~~ 280.

Please amend paragraph [0035] as follows:

[0035] Once disk substrate is positioned over receiving nest 280, gas flow from first port 220 is gradually stopped and gas flow through second port ~~422~~ 222 is initiated. Second port ~~422~~ 222 directs the gas flow through jets (not shown) disposed within pick-up head 212 that are aimed toward a hole formed by an inner diameter 283 of disk

substrate 250. The flow of gas through ID hole 283 creates a positive gas pressure cushion under disk substrate 250 to suspend it within receiving nest 280. As such, there is no mechanical contact between a surface of disk substrate 250 and parts of pickup head 212 and receiving nest 280 prior to the centering of disk substrate 250 relative to embossing foil 282.

Please amend paragraph [0038] as follows:

[0038] After imprinting disk substrate 250, gas may be directed through second port 422 222 and through jets (not shown) disposed within pick-up head 212 that are aimed toward a hole formed by an inner diameter 283 of disk substrate 250. The flow of gas through ID hole 283 creates a positive gas pressure cushion under disk substrate 250 to suspend it within receiving nest 280. Actuators 242, 244, 246 may be disengaged or released from the outer edge of disk substrate 250. Disk substrate 250 may then be removed from receiving nest 280 with pick-up head 212. As such, the flow of gas through the hole formed by inner diameter 283 aids in the removal of disk substrate 250 by pick-up head 212.